



IPC-A-610F with Amendment 1

Acceptability of Electronic Assemblies

If a conflict occurs between the English language and translated versions of this document, the English version will take precedence.

Developed by the IPC-A-610 development team including Task Group (7-31B), Task Group Asia (7-31BCN), Task Group Nordic (7-31BND), Task Group German Language (7-31BDE) and Task Group India (7-31BIN) of the Product Assurance Committees (7-30 and 7-30CN) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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IPC

Table of Contents

1 Foreword	1-1	2 Applicable Documents	2-1
1.1 Scope	1-2	2.1 IPC Documents	2-1
1.2 Purpose	1-3	2.2 Joint Industry Documents	2-1
1.3 Personnel Proficiency	1-3	2.3 EOS/ESD Association Documents	2-2
1.4 Classification	1-3	2.4 Electronics Industries Alliance Documents	2-2
1.5 Definition of Requirements	1-3	2.5 International Electrotechnical Commission Documents	2-2
1.5.1 Acceptance Criteria	1-4	2.6 ASTM	2-2
1.5.1.1 Target Condition	1-4	2.7 Technical Publications	2-2
1.5.1.2 Acceptable Condition	1-4	3 Handling Electronic Assemblies	3-1
1.5.1.3 Defect Condition	1-4	3.1 EOS/ESD Prevention	3-2
1.5.1.3.1 Disposition	1-4	3.1.1 Electrical Overstress (EOS)	3-3
1.5.1.4 Process Indicator Condition	1-4	3.1.2 Electrostatic Discharge (ESD)	3-4
1.5.1.4.1 Process Indicator Methodologies	1-4	3.1.3 Warning Labels	3-5
1.5.1.5 Combined Conditions	1-4	3.1.4 Protective Materials	3-6
1.5.1.6 Conditions Not Specified	1-5	3.2 EOS/ESD Safe Workstation/EPA	3-7
1.5.1.7 Specialized Designs	1-5	3.3 Handling Considerations	3-9
1.6 Terms and Definitions	1-5	3.3.1 Guidelines	3-9
1.6.1 Board Orientation	1-5	3.3.2 Physical Damage	3-10
1.6.1.1 *Primary Side	1-5	3.3.3 Contamination	3-10
1.6.1.2 *Secondary Side	1-5	3.3.4 Electronic Assemblies	3-11
1.6.1.3 *Solder Source Side	1-5	3.3.5 After Soldering	3-11
1.6.1.4 *Solder Destination Side	1-5	3.3.6 Gloves and Finger Cots	3-12
1.6.2 *Cold Solder Connection	1-5	4 Hardware	4-1
1.6.3 Electrical Clearance	1-5	4.1 Hardware Installation	4-2
1.6.4 FOD (Foreign Object Debris)	1-5	4.1.1 Electrical Clearance	4-2
1.6.5 High Voltage	1-5	4.1.2 Interference	4-3
1.6.6 Intrusive Solder	1-6	4.1.3 Component Mounting – High Power	4-4
1.6.7 Meniscus (Component)	1-6	4.1.4 Heatsinks	4-6
1.6.8 *Nonfunctional Land	1-6	4.1.4.1 Insulators and Thermal Compounds	4-6
1.6.9 Pin-in-Paste	1-6	4.1.4.2 Contact	4-8
1.6.10 Solder Balls	1-6	4.1.5 Threaded Fasteners and Other Threaded Hardware	4-9
1.6.11 Wire Diameter	1-6	4.1.5.1 Torque	4-11
1.6.12 Wire Overlap	1-6	4.1.5.2 Wires	4-13
1.6.13 Wire Overwrap	1-6		
1.7 Examples and Illustrations	1-6		
1.8 Inspection Methodology	1-6		
1.9 Verification of Dimensions	1-6		
1.10 Magnification Aids	1-6		
1.11 Lighting	1-7		

Table of Contents (cont.)

4.2 Jackpost Mounting	4-15	6.1.2 Rolled Flange	6-5
4.3 Connector Pins	4-16	6.1.3 Flared Flange	6-6
4.3.1 Edge Connector Pins	4-16	6.1.4 Controlled Split	6-7
4.3.2 Press Fit Pins	4-17	6.1.5 Solder	6-8
4.3.2.1 Soldering	4-20	6.2 Insulation	6-10
4.4 Wire Bundle Securing	4-23	6.2.1 Damage	6-10
4.4.1 General	4-23	6.2.1.1 Presolder	6-10
4.4.2 Lacing	4-26	6.2.1.2 Post-Solder	6-12
4.4.2.1 Damage	4-27	6.2.2 Clearance	6-13
4.5 Routing – Wires and Wire Bundles	4-28	6.2.3 Flexible Sleeve	6-15
4.5.1 Wire Crossover	4-28	6.2.3.1 Placement	6-15
4.5.2 Bend Radius	4-29	6.2.3.2 Damage	6-17
4.5.3 Coaxial Cable	4-30	6.3 Conductor	6-18
4.5.4 Unused Wire Termination	4-31	6.3.1 Deformation	6-18
4.5.5 Ties over Splices and Ferrules	4-32	6.3.2 Damage	6-19
5 Soldering	5-1	6.3.2.1 Stranded Wire	6-19
5.1 Soldering Acceptability Requirements	5-3	6.3.2.2 Solid Wire	6-20
5.2 Soldering Anomalies	5-4	6.3.3 Strand Separation (Birdcaging) – Presolder	6-20
5.2.1 Exposed Basis Metal	5-4	6.3.4 Strand Separation (Birdcaging) – Post-Solder	6-21
5.2.2 Pin Holes/Blow Holes	5-6	6.3.5 Tinning	6-22
5.2.3 Reflow of Solder Paste	5-7	6.4 Service Loops	6-24
5.2.4 Nonwetting	5-8	6.5 Stress Relief	6-25
5.2.5 Cold/Rosin Connection	5-9	6.5.1 Bundle	6-25
5.2.6 Dewetting	5-9	6.5.2 Lead/Wire Bend	6-26
5.2.7 Excess Solder	5-10	6.6 Lead/Wire Placement – General Requirements	6-28
5.2.7.1 Solder Balls	5-11	6.7 Solder – General Requirements	6-30
5.2.7.2 Bridging	5-12	6.8 Turrets and Straight Pins	6-31
5.2.7.3 Solder Webbing/Splashes	5-13	6.8.1 Lead/Wire Placement	6-31
5.2.8 Disturbed Solder	5-14	6.8.2 Turret and Straight Pin – Solder	6-33
5.2.9 Fractured Solder	5-15	6.9 Bifurcated	6-34
5.2.10 Solder Projections	5-16	6.9.1 Lead/Wire Placement – Side Route Attachments	6-34
5.2.11 Lead Free Fillet Lift	5-17	6.9.2 Lead/Wire Placement – Staked Wires	6-37
5.2.12 Lead Free Hot Tear/Shrink Hole	5-18	6.9.3 Lead/Wire Placement – Bottom and Top Route Attachments	6-38
5.2.13 Probe Marks and Other Similar Surface Conditions in Solder Joints	5-19	6.9.4 Solder	6-39
6 Terminal Connections	6-1	6.10 Slotted	6-42
6.1 Swaged Hardware	6-2	6.10.1 Lead/Wire Placement	6-42
6.1.1 Terminals	6-2	6.10.2 Solder	6-43
6.1.1.1 Terminal Base to Land Separation	6-2		
6.1.1.2 Turret	6-3		
6.1.1.3 Bifurcated	6-4		

Table of Contents (cont.)

6.11 Pierced/Perforated	6-44	7.2.2.1 Adhesive Bonding – Nonelevated Components	7-26
6.11.1 Lead/Wire Placement	6-44	7.2.2.2 Adhesive Bonding – Elevated Components	7-29
6.11.2 Solder	6-46	7.2.3 Other Devices	7-30
6.12 Hook	6-47	7.3 Supported Holes	7-31
6.12.1 Lead/Wire Placement	6-47	7.3.1 Axial Leaded – Horizontal	7-31
6.12.2 Solder	6-49	7.3.2 Axial Leaded – Vertical	7-33
6.13 Solder Cups	6-50	7.3.3 Wire/Lead Protrusion	7-35
6.13.1 Lead/Wire Placement	6-50	7.3.4 Wire/Lead Clinches	7-36
6.13.2 Solder	6-52	7.3.5 Solder	7-38
6.14 AWG 30 and Smaller Diameter Wires – Lead/Wire Placement	6-54	7.3.5.1 Vertical Fill (A)	7-41
6.15 Series Connected	6-55	7.3.5.2 Solder Destination Side – Lead to Barrel (B)	7-43
6.16 Edge Clip – Position	6-56	7.3.5.3 Solder Destination Side – Land Area Coverage (C)	7-45
7 Through-Hole Technology	7-1	7.3.5.4 Solder Source Side – Lead to Barrel (D)	7-46
7.1 Component Mounting	7-2	7.3.5.5 Solder Source Side – Land Area Coverage (E)	7-47
7.1.1 Orientation	7-2	7.3.5.6 Solder Conditions – Solder in Lead Bend	7-48
7.1.1.1 Orientation – Horizontal	7-3	7.3.5.7 Solder Conditions – Touching Through-Hole Component Body	7-49
7.1.1.2 Orientation – Vertical	7-5	7.3.5.8 Solder Conditions – Meniscus in Solder	7-50
7.1.2 Lead Forming	7-6	7.3.5.9 Lead Cutting after Soldering	7-52
7.1.2.1 Bend Radius	7-6	7.3.5.10 Coated Wire Insulation in Solder	7-53
7.1.2.2 Space between Seal/Weld and Bend	7-7	7.3.5.11 Interfacial Connection without Lead – Vias	7-54
7.1.2.3 Stress Relief	7-8	7.3.5.12 Board in Board	7-55
7.1.2.4 Damage	7-10	7.4 Unsupported Holes	7-58
7.1.3 Leads Crossing Conductors	7-11	7.4.1 Axial Leads – Horizontal	7-58
7.1.4 Hole Obstruction	7-12	7.4.2 Axial Leads – Vertical	7-59
7.1.5 DIP/SIP Devices and Sockets	7-13	7.4.3 Wire/Lead Protrusion	7-60
7.1.6 Radial Leads – Vertical	7-15	7.4.4 Wire/Lead Clinches	7-61
7.1.6.1 Spacers	7-16	7.4.5 Solder	7-63
7.1.7 Radial Leads – Horizontal	7-18	7.4.6 Lead Cutting after Soldering	7-65
7.1.8 Connectors	7-19	7.5 Jumper Wires	7-66
7.1.8.1 Right Angle	7-21	7.5.1 Wire Selection	7-66
7.1.8.2 Vertical Shrouded Pin Headers and Vertical Receptacle Connectors	7-22	7.5.2 Wire Routing	7-67
7.1.9 Conductive Cases	7-23	7.5.3 Wire Staking	7-69
7.2 Component Securing	7-23	7.5.4 Supported Holes	7-71
7.2.1 Mounting Clips	7-23	7.5.4.1 Supported Holes – Lead in Hole	7-71
7.2.2 Adhesive Bonding	7-25	7.5.5 Wrapped Attachment	7-72
		7.5.6 Lap Soldered	7-73

Table of Contents (cont.)

8 Surface Mount Assemblies	8-1	8.3.3.3 End Joint Width (C)	8-36
8.1 Staking Adhesive	8-3	8.3.3.4 Side Joint Length (D)	8-37
8.1.1 Component Bonding	8-3	8.3.3.5 Maximum Fillet Height (E)	8-38
8.1.2 Mechanical Strength	8-4	8.3.3.6 Minimum Fillet Height (F)	8-39
8.2 SMT Leads	8-6	8.3.3.7 Solder Thickness (G)	8-40
8.2.1 Plastic Components	8-6	8.3.3.8 End Overlap (J)	8-41
8.2.2 Damage	8-6	8.3.4 Castellated Terminations	8-42
8.2.3 Flattening	8-7	8.3.4.1 Side Overhang (A)	8-43
8.3 SMT Connections	8-7	8.3.4.2 End Overhang (B)	8-44
8.3.1 Chip Components – Bottom Only		8.3.4.3 Minimum End Joint Width (C)	8-44
Terminations	8-8	8.3.4.4 Minimum Side Joint Length (D)	8-45
8.3.1.1 Side Overhang (A)	8-9	8.3.4.5 Maximum Fillet Height (E)	8-45
8.3.1.2 End Overhang (B)	8-10	8.3.4.6 Minimum Fillet Height (F)	8-46
8.3.1.3 End Joint Width (C)	8-11	8.3.4.7 Solder Thickness (G)	8-46
8.3.1.4 Side Joint Length (D)	8-12	8.3.5 Flat Gull Wing Leads	8-47
8.3.1.5 Maximum Fillet Height (E)	8-13	8.3.5.1 Side Overhang (A)	8-47
8.3.1.6 Minimum Fillet Height (F)	8-13	8.3.5.2 Toe Overhang (B)	8-51
8.3.1.7 Solder Thickness (G)	8-14	8.3.5.3 Minimum End Joint Width (C)	8-52
8.3.1.8 End Overlap (J)	8-14	8.3.5.4 Minimum Side Joint Length (D)	8-54
8.3.2 Rectangular or Square End Chip		8.3.5.5 Maximum Heel Fillet Height (E)	8-56
Components – 1, 3 or 5 Side		8.3.5.6 Minimum Heel Fillet Height (F)	8-57
Terminations	8-15	8.3.5.7 Solder Thickness (G)	8-58
8.3.2.1 Side Overhang (A)	8-16	8.3.5.8 Coplanarity	8-59
8.3.2.2 End Overhang (B)	8-18	8.3.6 Round or Flattened (Coined) Gull	
8.3.2.3 End Joint Width (C)	8-19	Wing Leads	8-60
8.3.2.4 Side Joint Length (D)	8-21	8.3.6.1 Side Overhang (A)	8-61
8.3.2.5 Maximum Fillet Height (E)	8-22	8.3.6.2 Toe Overhang (B)	8-62
8.3.2.6 Minimum Fillet Height (F)	8-23	8.3.6.3 Minimum End Joint Width (C)	8-62
8.3.2.7 Solder Thickness (G)	8-24	8.3.6.4 Minimum Side Joint Length (D)	8-63
8.3.2.8 End Overlap (J)	8-25	8.3.6.5 Maximum Heel Fillet Height (E)	8-64
8.3.2.9 Termination Variations	8-26	8.3.6.6 Minimum Heel Fillet Height (F)	8-65
8.3.2.9.1 Mounting on Side (Billboarding)	8-26	8.3.6.7 Solder Thickness (G)	8-66
8.3.2.9.2 Mounting Upside Down	8-28	8.3.6.8 Minimum Side Joint Height (Q)	8-66
8.3.2.9.3 Stacking	8-29	8.3.6.9 Coplanarity	8-67
8.3.2.9.4 Tombstoning	8-30	8.3.7 J Leads	8-68
8.3.2.10 Center Terminations	8-31	8.3.7.1 Side Overhang (A)	8-68
8.3.2.10.1 Solder Width of Side Termination	8-31	8.3.7.2 Toe Overhang (B)	8-70
8.3.2.10.2 Minimum Fillet Height of Side Termination ...	8-32	8.3.7.3 End Joint Width (C)	8-70
8.3.3 Cylindrical End Cap Terminations	8-33	8.3.7.4 Side Joint Length (D)	8-72
8.3.3.1 Side Overhang (A)	8-34	8.3.7.5 Maximum Heel Fillet Height (E)	8-73
8.3.3.2 End Overhang (B)	8-35	8.3.7.6 Minimum Heel Fillet Height (F)	8-74
		8.3.7.7 Solder Thickness (G)	8-76
		8.3.7.8 Coplanarity	8-76

Table of Contents (cont.)

8.3.8 Butt/I Connections	8-77	8.3.16.3 Minimum End Joint Width (C)	8-104
8.3.8.1 Modified Through-Hole Terminations	8-77	8.3.16.4 Minimum Side Joint Length (D)	8-104
8.3.8.2 Solder Charged Terminations	8-78	8.3.16.5 Minimum Fillet Height (F)	8-105
8.3.8.3 Maximum Side Overhang (A)	8-79	8.4 Specialized SMT Terminations	8-106
8.3.8.4 Maximum Toe Overhang (B)	8-80	8.5 Surface Mount Connectors	8-107
8.3.8.5 Minimum End Joint Width (C)	8-81	8.6 Jumper Wires	8-108
8.3.8.6 Minimum Side Joint Length (D)	8-82	8.6.1 SMT	8-109
8.3.8.7 Maximum Fillet Height (E)	8-82	8.6.1.1 Chip and Cylindrical End Cap	
8.3.8.8 Minimum Fillet Height (F)	8-83	Components	8-109
8.3.8.9 Solder Thickness (G)	8-84	8.6.1.2 Gull Wing	8-110
8.3.9 Flat Lug Leads	8-85	8.6.1.3 J Lead	8-111
8.3.10 Tall Profile Components Having Bottom		8.6.1.4 Castellations	8-111
Only Terminations	8-86	8.6.1.5 Land	8-112
8.3.11 Inward Formed L-Shaped Ribbon Leads	8-87	9 Component Damage	9-1
8.3.12 Surface Mount Area Array	8-89	9.1 Loss of Metallization	9-2
8.3.12.1 Alignment	8-90	9.2 Chip Resistor Element	9-3
8.3.12.2 Solder Ball Spacing	8-90	9.3 Leaded/Leadless Devices	9-4
8.3.12.3 Solder Connections	8-91	9.4 Ceramic Chip Capacitors	9-8
8.3.12.4 Voids	8-93	9.5 Connectors	9-10
8.3.12.5 Underfill/Staking	8-93	9.6 Relays	9-13
8.3.12.6 Package on Package	8-94	9.7 Transformer Core Damage	9-13
8.3.13 Bottom Termination Components		9.8 Connectors, Handles, Extractors, Latches	9-14
(BTC)	8-96	9.9 Edge Connector Pins	9-15
8.3.14 Components with Bottom Thermal		9.10 Press Fit Pins	9-16
Plane Terminations	8-98	9.11 Backplane Connector Pins	9-17
8.3.15 Flattened Post Connections	8-100	9.12 Heat Sink Hardware	9-18
8.3.15.1 Maximum Termination Overhang –		9.13 Threaded Items and Hardware	9-19
Square Solder Land	8-100		
8.3.15.2 Maximum Termination Overhang –			
Round Solder Land	8-101		
8.3.15.3 Maximum Fillet Height	8-101		
8.3.16 P-Style Connections	8-102		
8.3.16.1 Maximum Side Overhang (A)	8-103		
8.3.16.2 Maximum Toe Overhang (B)	8-103		

Table of Contents (cont.)

10 Printed Circuit	10-1	10.6 Cleanliness	10-39
10.1 Non-Soldered Contact Areas	10-2	10.6.1 Flux Residues	10-40
10.1.1 Contamination	10-2	10.6.2 Foreign Object Debris (FOD)	10-41
10.1.2 Damage	10-4	10.6.3 Chlorides, Carbonates and White Residues	10-42
10.2 Laminate Conditions	10-4	10.6.4 Flux Residues – No-Clean Process – Appearance	10-44
10.2.1 Measling and Crazing	10-5	10.6.5 Surface Appearance	10-45
10.2.2 Blistering and Delamination	10-7	10.7 Solder Mask Coating	10-46
10.2.3 Weave Texture/Weave Exposure	10-9	10.7.1 Wrinkling/Cracking	10-47
10.2.4 Haloing	10-10	10.7.2 Voids, Blisters, Scratches	10-49
10.2.5 Edge Delamination, Nicks and Crazing	10-12	10.7.3 Breakdown	10-50
10.2.6 Burns	10-14	10.7.4 Discoloration	10-51
10.2.7 Bow and Twist	10-15	10.8 Conformal Coating	10-51
10.2.8 Depanelization	10-16	10.8.1 General	10-51
10.3 Conductors/Lands	10-18	10.8.2 Coverage	10-52
10.3.1 Reduction	10-18	10.8.3 Thickness	10-54
10.3.2 Lifted	10-19	10.8.4 Electrical Insulation Coating	10-55
10.3.3 Mechanical Damage	10-21	10.8.4.1 Coverage	10-55
10.4 Flexible and Rigid-Flex Printed Circuitry	10-22	10.8.4.2 Thickness	10-55
10.4.1 Damage	10-22	10.9 Encapsulation	10-56
10.4.2 Delamination/Blister	10-24	11 Discrete Wiring	11-1
10.4.2.1 Flex	10-24	11.1 Solderless Wrap	11-2
10.4.2.2 Flex to Stiffener	10-25	11.1.1 Number of Turns	11-3
10.4.3 Solder Wicking	10-26	11.1.2 Turn Spacing	11-4
10.4.4 Attachment	10-27	11.1.3 End Tails and Insulation Wrap	11-5
10.5 Marking	10-28	11.1.4 Raised Turns Overlap	11-7
10.5.1 Etched (Including Hand Printing)	10-30	11.1.5 Connection Position	11-8
10.5.2 Screened	10-31	11.1.6 Wire Dress	11-10
10.5.3 Stamped	10-33	11.1.7 Wire Slack	11-11
10.5.4 Laser	10-34	11.1.8 Wire Plating	11-12
10.5.5 Labels	10-35	11.1.9 Damaged Insulation	11-13
10.5.5.1 Bar Coding/Data Matrix	10-35	11.1.10 Damaged Conductors and Terminals	11-14
10.5.5.2 Readability	10-36	12 High Voltage	12-1
10.5.5.3 Labels – Adhesion and Damage	10-37	Appendix A Electrical Conductor Spacing	A-1
10.5.5.4 Position	10-37	Index	Index-1
10.5.6 Radio Frequency Identification (RFID) Tags	10-38		

Foreword

The following topics are addressed in this section:

1.1 Scope	1-2	1.6.1.2 *Secondary Side	1-5
1.2 Purpose	1-3	1.6.1.3 *Solder Source Side	1-5
1.3 Personnel Proficiency	1-3	1.6.1.4 *Solder Destination Side	1-5
1.4 Classification	1-3	1.6.2 *Cold Solder Connection	1-5
1.5 Definition of Requirements	1-3	1.6.3 Electrical Clearance	1-5
1.5.1 Acceptance Criteria	1-4	1.6.4 FOD (Foreign Object Debris)	1-5
1.5.1.1 Target Condition	1-4	1.6.5 High Voltage	1-5
1.5.1.2 Acceptable Condition	1-4	1.6.6 Intrusive Solder	1-6
1.5.1.3 Defect Condition	1-4	1.6.7 Meniscus (Component)	1-6
1.5.1.3.1 Disposition	1-4	1.6.8 *Nonfunctional Land	1-6
1.5.1.4 Process Indicator Condition	1-4	1.6.9 Pin-in-Paste	1-6
1.5.1.4.1 Process Indicator Methodologies	1-4	1.6.10 Solder Balls	1-6
1.5.1.5 Combined Conditions	1-4	1.6.11 Wire Diameter	1-6
1.5.1.6 Conditions Not Specified	1-5	1.6.12 Wire Overlap	1-6
1.5.1.7 Specialized Designs	1-5	1.6.13 Wire Overwrap	1-6
1.6 Terms and Definitions	1-5	1.7 Examples and Illustrations	1-6
1.6.1 Board Orientation	1-5	1.8 Inspection Methodology	1-6
1.6.1.1 *Primary Side	1-5	1.9 Verification of Dimensions	1-6
		1.10 Magnification Aids	1-6
		1.11 Lighting	1-7

Foreword (cont.)

1.1 Scope This standard is a collection of visual quality acceptability requirements for electronic assemblies. This standard does not provide criteria for cross-section evaluation.

This document presents acceptance requirements for the manufacture of electrical and electronic assemblies. Historically, electronic assembly standards contained a more comprehensive tutorial addressing principles and techniques. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001, IPC-AJ-820 and IPC J-STD-001.

The criteria in this standard are not intended to define processes to accomplish assembly operations nor is it intended to authorize repair/modification or change of the customer's product. For instance, the presence of criteria for adhesive bonding of components does not imply/authorize/require the use of adhesive bonding, and the depiction of a lead wrapped clockwise around a terminal does not imply/authorize/require that all leads/wires be wrapped in the clockwise direction.

Users of this standard should be knowledgeable of the applicable requirements of the document and how to apply them.

Objective evidence of the demonstration of this knowledge should be maintained. Where objective evidence is unavailable, the organization should consider periodic review of personnel skills to determine visual acceptance criteria appropriately.

IPC-A-610 has criteria outside the scope of IPC J-STD-001 defining handling, mechanical and other workmanship requirements. Table 1-1 is a summary of related documents.

Table 1-1 Summary of Related Documents

Document Purpose	Specification Number	Definition
Design Standard	IPC-2220 (Series) IPC-7351 IPC-CM-770	Design requirements reflecting three levels of complexity (Levels A, B, and C) indicating finer geometries, greater densities, more process steps to produce the product. Component and Assembly Process Guidelines to assist in the design of the bare board and the assembly where the bare board processes concentrate on land patterns for surface mount and the assembly concentrates on surface mount and through-hole principles which are usually incorporated into the design process and the documentation.
PCB Requirements	IPC-6010 (series) IPC-A-600	Requirements and acceptance documentation for rigid, rigid flex, flex and other types of substrates.
End Item Documentation	IPC-D-325	Documentation depicting bare board specific end product requirements designed by the customer or end item assembly requirements. Details may or may not reference industry specifications or workmanship standards as well as customer's own preferences or internal standard requirements.
End Item Standards	IPC J-STD-001	Requirements for soldered electrical and electronic assemblies depicting minimum end product acceptable characteristics as well as methods for evaluation (test methods), frequency of testing and applicable ability of process control requirements.
Acceptability Standard	IPC-A-610	Pictorial interpretive document indicating various characteristics of the board and/or assembly as appropriate relating to desirable conditions that exceed the minimum acceptable characteristics indicated by the end item performance standard and reflect various out-of-control (process indicator or defect) conditions to assist the shop process evaluators in judging need for corrective action.
Training Programs (Optional)		Documented training requirements for teaching and learning process procedures and techniques for implementing acceptance requirements of either end item standards, acceptability standards, or requirements detailed on the customer documentation.
Rework and Repair	IPC-7711/7721	Documentation providing the procedures to accomplish conformal coating and component removal and replacement, solder resist repair, and modification/repair of laminate material, conductors, and plated-through holes.